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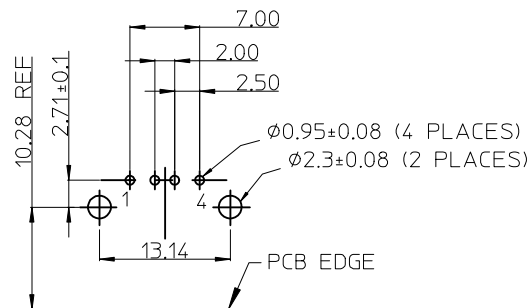
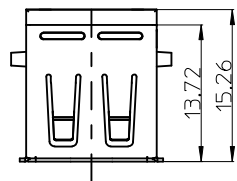
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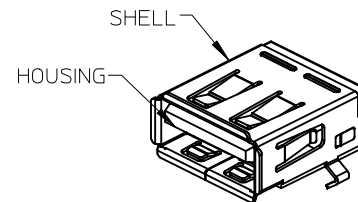
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PCB LAYOUT (TOP VIEW)



NOTES:

1. MATERIAL:

- ① METAL SHELL: COPPER ALLOY.
 ② HOUSING: SEE CHART, 30% GLASS FIBER FILLED, UL94-V0.
 ③ TERMINAL: PHOSPHOR BRONZE

2. TERMINAL:

CONTACT AREA: (a) GOLD FLASH.

(b) GOLD (Au), THICKNESS=0.76μm/ 30μINCH MINIMUM.

SOLDER TAIL: TIN PLATED, THICKNESS=1.9μm/ 75μINCH MINIMUM.

UNDER PLATED: NICKEL (Ni), THICKNESS=1.25μm/ 50μINCH MINIMUM.

METAL SHELL: SEE CHART.

3. RECOMMENDED PCB THICKNESS: SEE CHART

4. PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002

FOR NON IR REFER TO PS-67643-003

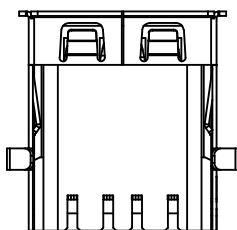
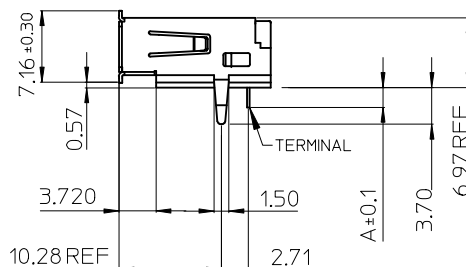
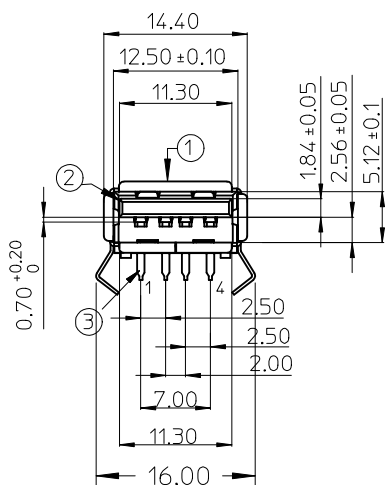
5. TORQUE FORCE SPEC: 2.50kg-cm Min, MEASURED AT BROKEN POINT.

6. TEST SUMMARY: FOR IR REFER TO TS-67643-002

FOR NON IR REFER TO TS-67643-003

7. PACKAGE: REFER TO PK-67643-002

8. LEAD FREE AND ROHS COMPLIANT PRODUCT



REVISED	EC NO:	DRWN:FYANG05	CHKD:	APPR:	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
								mm	INCH	MM ONLY		1:1	METRIC			
							4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)				
							3 PLACES	± ---	± ---	IVY-LIN	2005/03/31					
							2 PLACES	± 0.25	± ---	CHECKED BY	DATE	MOLEX MOLEX INCORPORATED				
1 PLACE	± 0.25	± ---	ALL IN	2005/03/31												
							ANGULAR ± 3 °			APPROVED BY	DATE	SHEET NO. 1 OF 2				
							DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			WWSCHANG	2005/03/31					
										MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
										SIZE						
										A 4						

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P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0910	POLYESTER	BLACK	GOLD FLASH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS= 2.54μM/100μM INCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	NON IR
67643-1910	POLYESTER	WHITE			REFLOW PROCESS
67643-2910	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3910	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
67643-0911	POLYESTER	BLACK	GOLD PLATING 0.76μM/30μM INCH	NON IR REFLOW PROCESS: MATTE TIN PLATED. THICKNESS= 2.00μM/80μM INCH MINIMUM UNDER PLATE:NICKEL (Ni).	NON IR
67643-1911	POLYESTER	WHITE			REFLOW PROCESS
67643-2911	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3911	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
PCB THICKNESS		1.60±0.05			
DIMENSION "A"		2.60			

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0930	HIGH TEMPERATURE NYLON	BLACK	GOLD FLASH	FOR IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS= 2.54μM/100μM INCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	FOR IR REFLOW PROCESS
67643-1930	HIGH TEMPERATURE NYLON	WHITE			
67643-0931	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 0.76μM /30μM INCH		
67643-1931	HIGH TEMPERATURE NYLON	WHITE			
PCB THICKNESS		1.20±0.05			
DIMENSION "A"		2.00			

REVISED EC NO: DRWN:FYANG05 CHKD: APPR:	2013/05/09	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
					mm	INCH	DRAWN BY DATE		TITLE		
				4 PLACES	± ---	± ---	IVY-LIN 2005/03/31		USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION) MOLEX MOLEX INCORPORATED		
				3 PLACES	± ---	± ---	CHECKED BY DATE				
				2 PLACES	± 0.25	± ---	ALL IN 2005/03/31				
				1 PLACE	± 0.25	± ---	APPROVED BY DATE				
				ANGULAR ± 3 °			WWSCHANG 2005/03/31				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO.		DOCUMENT NO.		SHEET NO.				
			SIZE A4		SEE TABLE		SD-67643-003		2 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

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